

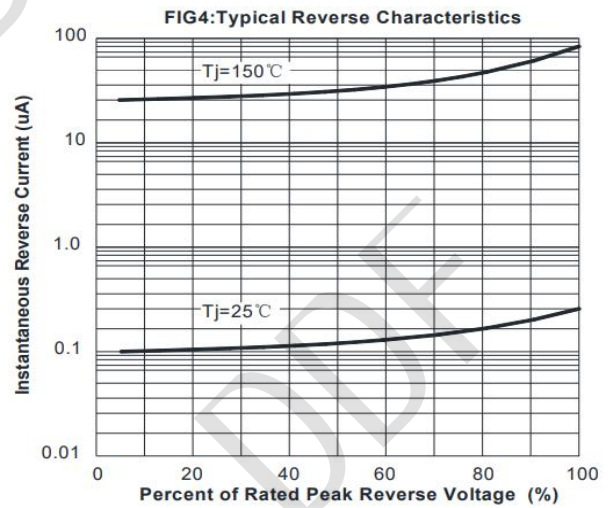
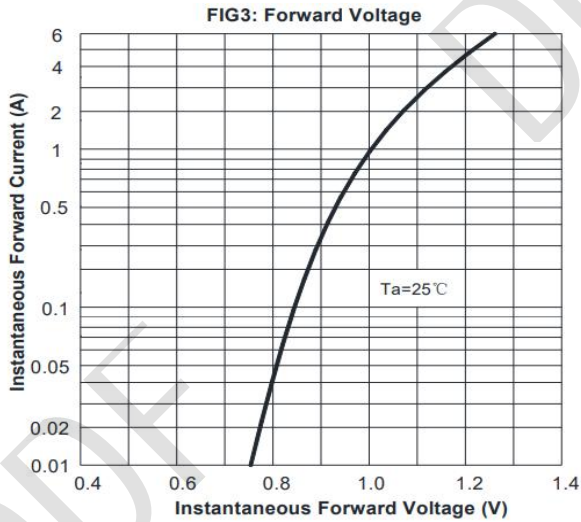
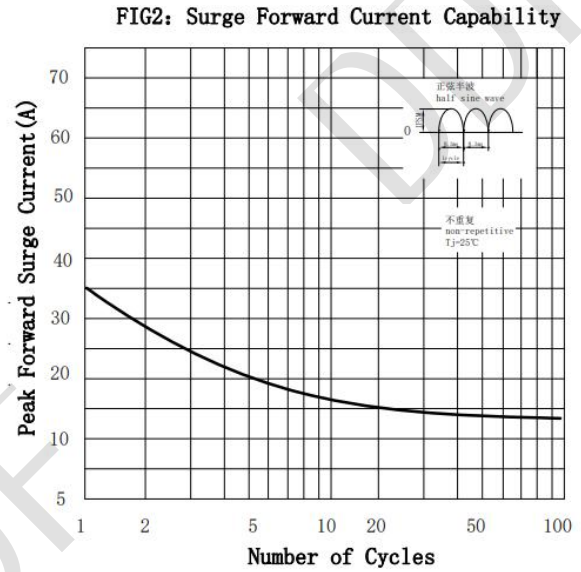
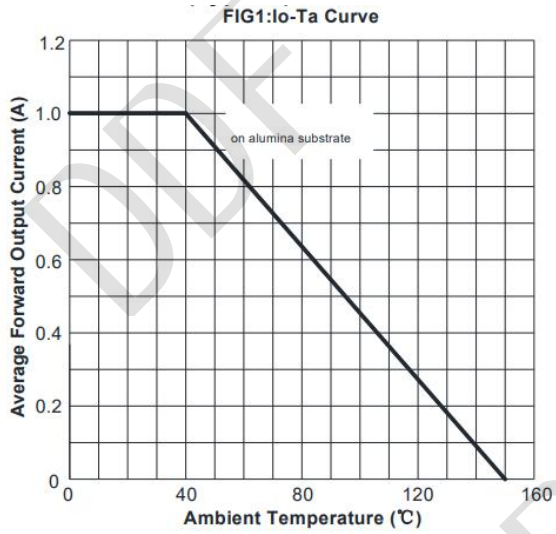
ABS2 THRU ABS10

	反向电压：200--1000 伏 REVERSE VOLTAGE: 200 to 1000 VOLTS 正向电流：1 安培 FORWARD CURRENT: 1 AMPERE					
	特征 FEATURES					
	<ul style="list-style-type: none"> ● 玻璃钝化芯片 Glass Passivated Die Construction ● 正向浪涌承受能力强 High Forward surge capability ● 低正向压降 Low Forward Voltage Drop ● 高温焊接保证 High temperature soldering aranted:260°C/10 秒 ● 引线 and 管体皆符合 RoHS 标准 Lead and body according with RoHS standard 					
	机械数据 Mechanical Date					
<ul style="list-style-type: none"> ● 封装：ABS 封装 ABS small outline plaskage ● 极性：按极性激光印字与脚位 As Markedon Case ● 环氧树脂 UL 易燃等级 Epoxy UL:94V-0 ● 安装位置：任意 Mounting Position:Any 						

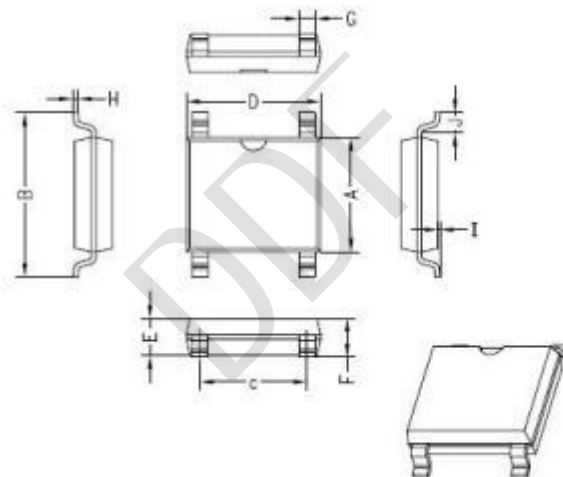
极限值和温度特性 (TA=25°C 除非另有规定) Ratings at 25°C ambient temperature unless otherwise specified

参数 Parameters	符号 Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	Units
最大可重复峰值反向电压 Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	800	1000	Volts
最大直流阻断电压 Maximum DC Blocking oltage	VDC	200	400	600	800	1000	Volts
最大正向平均整流电流 Maximum Average Forward Rectified Curren@Ta=40° C	$I_{(AV)}$	1					Amp
正向不重复浪涌电流 8.3ms单一正弦半波 Peak Forward Surge Current,8.3ms single half-sine-wave superimposed on rated load	I_{FSM}	35					Amp
单位时间内承受的最大电流 I^2t Rating for Fusing(t<8.3ms)	I^2t	5					A ² s
最大正向电压 Maximum Forward Voltage at 0.5A DC and 25°C	V_F	1.0					Volts
最大反向电流@VDC Maximum Reverse Current at Ta=25°C	I_R	5.0					uAmp
最大反向电流@VDC Maximum Reverse Current at Ta=125°C		500					
典型结电容 VR=4.0V, f=1MHZ Typical Junction Capacitance	C_J	13					PF
典型热阻 Typical Thermal Resistance	$R_{\theta JA}$	60					°C/W
工作结温和存储温度 Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150					°C

特性曲线 Characteristic Curves ($T_A=25\text{ }^{\circ}\text{C}$ unless otherwise noted)



外形尺寸 mm (Outline Dimensions mm)



ABS

Dim	Min	Max
A	4.3	4.5
B	6.0	6.4
C	3.9	4.1
D	4.9	5.1
E	1.25	1.45
F	1.45	1.6
G	0.56	0.84
H	0.15	0.35
I	0.05	0.2
J	0.3	0.8